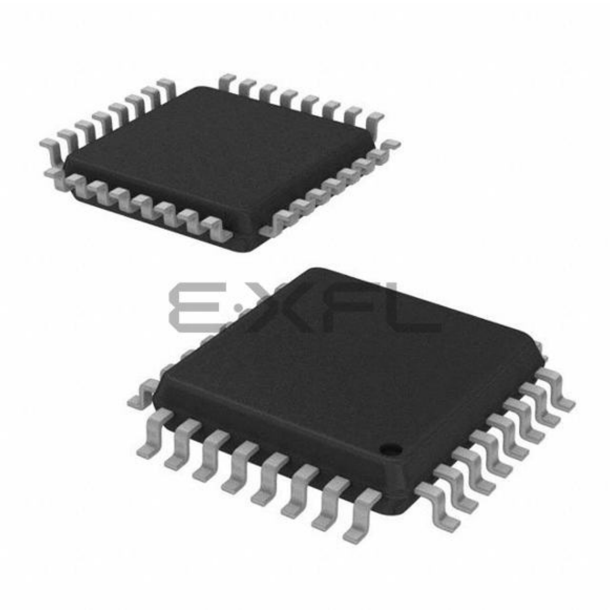


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I²C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s08dz16f1clc

Table 1-2 provides the functional version of the on-chip modules.

Table 1-2. Module Versions

Module		Version
Central Processor Unit	(CPU)	3
Multi-Purpose Clock Generator	(MCG)	1
Analog Comparator	(ACMP)	3
Analog-to-Digital Converter	(ADC)	1
Inter-Integrated Circuit	(IIC)	2
Freescale's CAN	(MSCAN)	1
Serial Peripheral Interface	(SPI)	3
Serial Communications Interface	(SCI)	4
Real-Time Counter	(RTC)	1
Timer Pulse Width Modulator	(TPM)	3[1]
Debug Module	(DBG)	2

1 3M05C and older masks have TPM version 2.

1.3 System Clock Distribution

Figure 1-2 shows a simplified clock connection diagram. Some modules in the MCU have selectable clock inputs as shown. The clock inputs to the modules indicate the clock(s) that are used to drive the module function.

The following are the clocks used in this MCU:

- BUSCLK — The frequency of the bus is always half of MCGOUT.
- LPO — Independent 1-kHz clock that can be selected as the source for the COP and RTC modules.
- MCGOUT — Primary output of the MCG and is twice the bus frequency.
- MCGLCLK — Development tools can select this clock source to speed up BDC communications in systems where BUSCLK is configured to run at a very slow frequency.
- MCGERCLK — External reference clock can be selected as the RTC clock source. It can also be used as the alternate clock for the ADC and MSCAN.
- MCGIRCLK — Internal reference clock can be selected as the RTC clock source.
- MCGFFCLK — Fixed frequency clock can be selected as clock source for the TPM1 and TPM2.
- TPM1CLK — External input clock source for TPM1.
- TPM2CLK — External input clock source for TPM2.

Table 4-2. Direct-Page Register Summary (Sheet 3 of 3)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x0050	SPIC1	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
0x0051	SPIC2	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
0x0052	SPIBR	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
0x0053	SPIS	SPRF	0	SPTEF	MODF	0	0	0	0
0x0054	Reserved	0	0	0	0	0	0	0	0
0x0055	SPID	Bit 7	6	5	4	3	2	1	Bit 0
0x0056– 0x0057	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0058	IICA	AD7	AD6	AD5	AD4	AD3	AD2	AD1	0
0x0059	IICF	MULT		ICR					
0x005A	IICC1	IICEN	IICIE	MST	TX	TXAK	RSTA	0	0
0x005B	IICS	TCF	IAAS	BUSY	ARBL	0	SRW	IICIF	RXAK
0x005C	IICD	DATA							
0x005D	IICC2	GCAEN	ADEXT	0	0	0	AD10	AD9	AD8
0x005E– 0x005F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0060	TPM2SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0061	TPM2CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x0062	TPM2CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x0063	TPM2MODH	Bit 15	14	13	12	11	10	9	Bit 8
0x0064	TPM2MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x0065	TPM2C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0066	TPM2C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0067	TPM2C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0068	TPM2C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x0069	TPM2C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x006A	TPM2C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x006B	Reserved	—	—	—	—	—	—	—	—
0x006C	RTCSC	RTIF	RTCLKS		RTIE	RTCPS			
0x006D	RTCCNT	RTCCNT							
0x006E	RTCMOD	RTCMOD							
0x006F	Reserved	—	—	—	—	—	—	—	—
0x0070– 0x007F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —

High-page registers, shown in Table 4-3, are accessed much less often than other I/O and control registers so they have been located outside the direct addressable memory space, starting at 0x1800.

Table 4-12. FPROT Register Field Descriptions

Field	Description
7:6 EPS	**EEPROM Protect Select Bits** — This 2-bit field determines the protected EEPROM locations that cannot be erased or programmed. See Table 4-13.
5:0 FPS	**Flash Protect Select Bits** — This 6-bit field determines the protected Flash locations that cannot be erased or programmed. SeeTable 4-14.

Table 4-13. EEPROM Block Protection

EPS	Address Area Protected	Memory Size Protected (bytes)	Number of Sectors Protected
0x3	N/A	0	0
0x2	0x17F0 - 0x17FF	32	4
0x1	0x17E0 - 0x17FF	64	8
0x0	0x17C0–0x17FF	128	16

Table 4-14. Flash Block Protection

FPS	Address Area Protected	Memory Size Protected (bytes)	Number of Sectors Protected
0x3F	N/A	0	0
0x3E	0xFA00–0xFFFF	1.5K	2
0x3D	0xF400–0xFFFF	3K	4
0x3C	0xEE00–0xFFFF	4.5K	6
0x3B	0xE800–0xFFFF	6K	8
...	...	...	...
0x37	0xD000–0xFFFF	12K	16
0x36	0xCA00–0xFFFF	13.5K	18
0x35	0xC400–0xFFFF	15K	20
0x34	0xBE00–0xFFFF	16.5K	22
...	...	...	...
0x2C	0x8E00–0xFFFF	28.5K	38
0x2B	0x8800–0xFFFF	30K	40
0x2A	0x8200–0xFFFF	31.5K	42
0x29	0x7C00–0xFFFF	33K	44
...	...	...	...
0x22	0x5200–0xFFFF	43.5K	58
0x21	0x4C00–0xFFFF	45K	60
0x20	0x4600–0xFFFF	46.5K	62
0x1F	0x4000–0xFFFF	48K	64
...	...	...	...

5.8.6 System Device Identification Register (SDIDH, SDIDL)

These high page read-only registers are included so host development systems can identify the HCS08 derivative and revision number. This allows the development software to recognize where specific memory blocks, registers, and control bits are located in a target MCU.

	7	6	5	4	3	2	1	0
R	Reserved				ID11	ID10	ID9	ID8
W								
Reset:	0[1]	0[1]	0[1]	0[1]	0	0	0	0

= Unimplemented or Reserved

[1] The revision number that is hard coded into these bits reflects the current silicon revision level.

Figure 5-7. System Device Identification Register — High (SDIDH)

Table 5-8. SDIDH Register Field Descriptions

Field	Description
3:0 ID[11:8]	**Part Identification Number** — MC9S08DZ60 Series MCUs are hard-coded to the value 0x00E. See also ID bits in Table 5-9.

	7	6	5	4	3	2	1	0
R	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
W								
Reset:	0	0	0	0	1	1	1	0

= Unimplemented or Reserved

Figure 5-8. System Device Identification Register — Low (SDIDL)

Table 5-9. SDIDL Register Field Descriptions

Field	Description
7:0 ID[7:0]	**Part Identification Number** — MC9S08DZ60 Series MCUs are hard-coded to the value 0x00E. See also ID bits in Table 5-8.

6.5.7 Port G Registers

Port G is controlled by the registers listed below.

6.5.7.1 Port G Data Register (PTGD)

	7	6	5	4	3	2	1	0
R	0	0	PTGD5	PTGD4	PTGD3	PTGD2	PTGD1	PTGD0
W								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 6-42. Port G Data Register (PTGD)

Table 6-40. PTGD Register Field Descriptions

Field	Description
5:0 PTGD[5:0]	**Port G Data Register Bits** — For port G pins that are inputs, reads return the logic level on the pin. For port G pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port G pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTGD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.

6.5.7.2 Port G Data Direction Register (PTGDD)

	7	6	5	4	3	2	1	0
R	0	0	PTGDD5	PTGDD4	PTGDD3	PTGDD2	PTGDD1	PTGDD0
W								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 6-43. Port G Data Direction Register (PTGDD)

Table 6-41. PTGDD Register Field Descriptions

Field	Description
5:0 PTGDD[5:0]	**Data Direction for Port G Bits** — These read/write bits control the direction of port G pins and what is read for PTGD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port G bit n and PTGD reads return the contents of PTGDn.

- — If entering FEE, set RDIV appropriately, clear the IREFS bit to switch to the external reference, and leave the CLKS bits at %00 so that the output of the FLL is selected as the system clock source.
- — If entering FBE, clear the IREFS bit to switch to the external reference and change the CLKS bits to %10 so that the external reference clock is selected as the system clock source. The RDIV bits should also be set appropriately here according to the external reference frequency because although the FLL is bypassed, it is still on in FBE mode.
- — The internal reference can optionally be kept running by setting the IRCLKEN bit. This is useful if the application will switch back and forth between internal and external modes. For minimum power consumption, leave the internal reference disabled while in an external clock mode.

3. After the proper configuration bits have been set, wait for the affected bits in the MCGSC register to be changed appropriately, reflecting that the MCG has moved into the proper mode.
   - — If ERCLKEN was set in step 1 or the MCG is in FEE, FBE, PEE, PBE, or BLPE mode, and EREFS was also set in step 1, wait here for the OSCINIT bit to become set indicating that the external clock source has finished its initialization cycles and stabilized. Typical crystal startup times are given in Appendix A, “Electrical Characteristics”.
   - — If in FEE mode, check to make sure the IREFST bit is cleared and the LOCK bit is set before moving on.
   - — If in FBE mode, check to make sure the IREFST bit is cleared, the LOCK bit is set, and the CLKST bits have changed to %10 indicating the external reference clock has been appropriately selected. Although the FLL is bypassed in FBE mode, it is still on and will lock in FBE mode.

To change from FEI clock mode to FBI clock mode, follow this procedure:

1. Change the CLKS bits to %01 so that the internal reference clock is selected as the system clock source.
2. Wait for the CLKST bits in the MCGSC register to change to %01, indicating that the internal reference clock has been appropriately selected.

8.5.2 MCG Mode Switching

When switching between operational modes of the MCG, certain configuration bits must be changed in order to properly move from one mode to another. Each time any of these bits are changed (PLLS, IREFS, CLKS, or EREFS), the corresponding bits in the MCGSC register (PLLST, IREFST, CLKST, or OSCINIT) must be checked before moving on in the application software.

Additionally, care must be taken to ensure that the reference clock divider (RDIV) is set properly for the mode being switched to. For instance, in PEE mode, if using a 4 MHz crystal, RDIV must be set to %001 (divide-by-2) or %010 (divide -by-4) in order to divide the external reference down to the required frequency between 1 and 2 MHz.

The RDIV and IREFS bits should always be set properly before changing the PLLS bit so that the FLL or PLL clock has an appropriate reference clock frequency to switch to.

Chapter 10
Analog-to-Digital Converter (S08ADC12V1)

10.1 Introduction

The 12-bit analog-to-digital converter (ADC) is a successive approximation ADC designed for operation within an integrated microcontroller system-on-chip.

NOTE

MC9S08DZ60 Series devices operate at a higher voltage range (2.7 V to 5.5 V) and do not include stop1 mode. Please ignore references to stop1.

10.1.1 Analog Power and Ground Signal Names

References to V_{DDAD} and V_{SSAD} in this chapter correspond to signals V_{DDA} and V_{SSA}, respectively.

10.1.2 Channel Assignments

NOTE

The ADC channel assignments for the MC9S08DZ60 Series devices are shown in Table 10-1. Reserved channels convert to an unknown value.

This chapter shows bits for all S08ADC12V1 channels. MC9S08DZ60 Series MCUs do not use all of these channels. All bits corresponding to channels that are not available on a device are reserved.

When a conversion is aborted, the contents of the data registers, ADCRH and ADCRL, are not altered. However, they continue to be the values transferred after the completion of the last successful conversion. If the conversion was aborted by a reset, ADCRH and ADCRL return to their reset states.

10.4.4.4 Power Control

The ADC module remains in its idle state until a conversion is initiated. If ADACK is selected as the conversion clock source, the ADACK clock generator is also enabled.

Power consumption when active can be reduced by setting ADLPC. This results in a lower maximum value for f_{ADCK} (see the electrical specifications).

10.4.4.5 Sample Time and Total Conversion Time

The total conversion time depends on the sample time (as determined by ADLSMP), the MCU bus frequency, the conversion mode (8-bit, 10-bit or 12-bit), and the frequency of the conversion clock (f_{ADCK}). After the module becomes active, sampling of the input begins. ADLSMP selects between short (3.5 ADCK cycles) and long (23.5 ADCK cycles) sample times.When sampling is complete, the converter is isolated from the input channel and a successive approximation algorithm is performed to determine the digital value of the analog signal. The result of the conversion is transferred to ADCRH and ADCRL upon completion of the conversion algorithm.

If the bus frequency is less than the f_{ADCK} frequency, precise sample time for continuous conversions cannot be guaranteed when short sample is enabled (ADLSMP=0). If the bus frequency is less than 1/11th of the f_{ADCK} frequency, precise sample time for continuous conversions cannot be guaranteed when long sample is enabled (ADLSMP=1).

The maximum total conversion time for different conditions is summarized in Table 10-13.

Table 10-13. Total Conversion Time vs. Control Conditions

Conversion Type	ADICLK	ADLSMP	Max Total Conversion Time
Single or first continuous 8-bit	0x, 10	0	20 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	0x, 10	0	23 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	0x, 10	1	40 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	0x, 10	1	43 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	11	0	5 μs + 20 ADCK + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	11	0	5 μs + 23 ADCK + 5 bus clock cycles
Single or first continuous 8-bit	11	1	5 μs + 40 ADCK + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	11	1	5 μs + 43 ADCK + 5 bus clock cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	17 ADCK cycles
Subsequent continuous 10-bit or 12-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	20 ADCK cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}/11$	xx	1	37 ADCK cycles

11.1.1 Features

The IIC includes these distinctive features:

- Compatible with IIC bus standard
- Multi-master operation
- Software programmable for one of 64 different serial clock frequencies
- Software selectable acknowledge bit
- Interrupt driven byte-by-byte data transfer
- Arbitration lost interrupt with automatic mode switching from master to slave
- Calling address identification interrupt
- Start and stop signal generation/detection
- Repeated start signal generation
- Acknowledge bit generation/detection
- Bus busy detection
- General call recognition
- 10-bit address extension

11.1.2 Modes of Operation

A brief description of the IIC in the various MCU modes is given here.

- **Run mode** — This is the basic mode of operation. To conserve power in this mode, disable the module.
- **Wait mode** — The module continues to operate while the MCU is in wait mode and can provide a wake-up interrupt.
- **Stop mode** — The IIC is inactive in stop3 mode for reduced power consumption. The stop instruction does not affect IIC register states. Stop2 resets the register contents.

the transition from master to slave mode does not generate a stop condition. Meanwhile, a status bit is set by hardware to indicate loss of arbitration.

11.4.1.7 Clock Synchronization

Because wire-AND logic is performed on the SCL line, a high-to-low transition on the SCL line affects all the devices connected on the bus. The devices start counting their low period and after a device's clock has gone low, it holds the SCL line low until the clock high state is reached. However, the change of low to high in this device clock may not change the state of the SCL line if another device clock is still within its low period. Therefore, synchronized clock SCL is held low by the device with the longest low period. Devices with shorter low periods enter a high wait state during this time (see Figure 11-10). When all devices concerned have counted off their low period, the synchronized clock SCL line is released and pulled high. There is then no difference between the device clocks and the state of the SCL line and all the devices start counting their high periods. The first device to complete its high period pulls the SCL line low again.

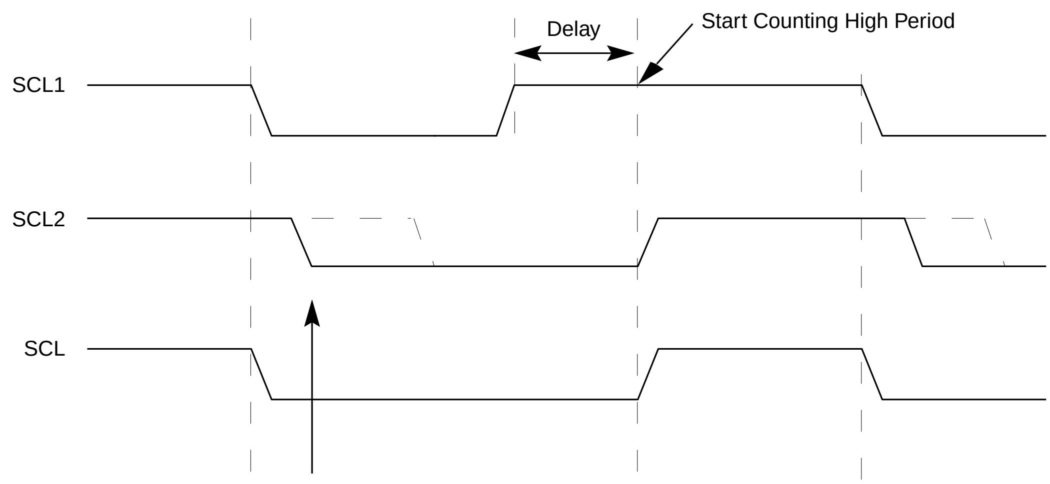


Figure 11-10. IIC Clock Synchronization

11.4.1.8 Handshaking

The clock synchronization mechanism can be used as a handshake in data transfer. Slave devices may hold the SCL low after completion of one byte transfer (9 bits). In such a case, it halts the bus clock and forces the master clock into wait states until the slave releases the SCL line.

11.4.1.9 Clock Stretching

The clock synchronization mechanism can be used by slaves to slow down the bit rate of a transfer. After the master has driven SCL low the slave can drive SCL low for the required period and then release it. If the slave SCL low period is greater than the master SCL low period then the resulting SCL bus signal low period is stretched.

Chapter 16
Timer Pulse-Width Modulator (S08TPMV3)

NOTE

This chapter refers to S08TPM version 3, which applies to the 0M74K and newer mask sets of this device. 3M05C and older mask set devices use S08TPM version 2. If your device uses mask 3M05C or older, please refer to Appendix B, “Timer Pulse-Width Modulator (TPMV2) on page 391 for information pertaining to that module.

16.1 Introduction

The TPM is a one-to-eight-channel timer system which supports traditional input capture, output compare, or edge-aligned PWM on each channel. A control bit allows the TPM to be configured such that all channels may be used for center-aligned PWM functions. Timing functions are based on a 16-bit counter with prescaler and modulo features to control frequency and range (period between overflows) of the time reference. This timing system is ideally suited for a wide range of control applications, and the center-aligned PWM capability extends the field of application to motor control in small appliances.

The TPM uses one input/output (I/O) pin per channel, TPMxCHn, where x is the TPM number (for example, 1 or 2) and n is the channel number (for example, 0–5). The TPM shares its I/O pins with general-purpose I/O port pins (refer to the Pins and Connections chapter for more information).

MC9S08DZ60 Series MCUs have two TPM modules. In all packages, TPM2 is 2-channel. The number of channels available on external pins in TPM1 depends on the package:

- Six channels in 64-pin and 48-pin packages
- Four channels in 32-pin packages.

16.2.1.1 EXTCLK — External Clock Source

Control bits in the timer status and control register allow the user to select nothing (timer disable), the bus-rate clock (the normal default source), a crystal-related clock, or an external clock as the clock which drives the TPM prescaler and subsequently the 16-bit TPM counter. The external clock source is synchronized in the TPM. The bus clock clocks the synchronizer; the frequency of the external source must be no more than one-fourth the frequency of the bus-rate clock, to meet Nyquist criteria and allowing for jitter.

The external clock signal shares the same pin as a channel I/O pin, so the channel pin will not be usable for channel I/O function when selected as the external clock source. It is the user's responsibility to avoid such settings. If this pin is used as an external clock source (CLKSB:CLKSA = 1:1), the channel can still be used in output compare mode as a software timer (ELSnB:ELSnA = 0:0).

16.2.1.2 TPMxCHn — TPM Channel n I/O Pin(s)

Each TPM channel is associated with an I/O pin on the MCU. The function of this pin depends on the channel configuration. The TPM pins share with general purpose I/O pins, where each pin has a port data register bit, and a data direction control bit, and the port has optional passive pullups which may be enabled whenever a port pin is acting as an input.

The TPM channel does not control the I/O pin when (ELSnB:ELSnA = 0:0) or when (CLKSB:CLKSA = 0:0) so it normally reverts to general purpose I/O control. When CPWMS = 1 (and ELSnB:ELSnA not = 0:0), all channels within the TPM are configured for center-aligned PWM and the TPMxCHn pins are all controlled by the TPM system. When CPWMS=0, the MSnB:MSnA control bits determine whether the channel is configured for input capture, output compare, or edge-aligned PWM.

When a channel is configured for input capture (CPWMS=0, MSnB:MSnA = 0:0 and ELSnB:ELSnA not = 0:0), the TPMxCHn pin is forced to act as an edge-sensitive input to the TPM. ELSnB:ELSnA control bits determine what polarity edge or edges will trigger input-capture events. A synchronizer based on the bus clock is used to synchronize input edges to the bus clock. This implies the minimum pulse width—that can be reliably detected—on an input capture pin is four bus clock periods (with ideal clock pulses as near as two bus clocks can be detected). TPM uses this pin as an input capture input to override the port data and data direction controls for the same pin.

When a channel is configured for output compare (CPWMS=0, MSnB:MSnA = 0:1 and ELSnB:ELSnA not = 0:0), the associated data direction control is overridden, the TPMxCHn pin is considered an output controlled by the TPM, and the ELSnB:ELSnA control bits determine how the pin is controlled. The remaining three combinations of ELSnB:ELSnA determine whether the TPMxCHn pin is toggled, cleared, or set each time the 16-bit channel value register matches the timer counter.

When the output compare toggle mode is initially selected, the previous value on the pin is driven out until the next output compare event—then the pin is toggled.

TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from $FFFE to $FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to $0000.

— Center-Aligned PWM (Section 16.4.2.4, "Center-Aligned PWM Mode)

In this mode and if (CLKSB:CLKSA not = 00), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer after that the both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from $FFFE to $FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to (TPMxMODH:L - 1).

5. Center-Aligned PWM (Section 16.4.2.4, "Center-Aligned PWM Mode)

— TPMxCnVH:L = TPMxMODH:L [SE110-TPM case 1]

In this case, the TPM v3 produces 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.

— TPMxCnVH:L = (TPMxMODH:L - 1) [SE110-TPM case 2]

In this case, the TPM v3 produces almost 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.

— TPMxCnVH:L is changed from 0x0000 to a non-zero value [SE110-TPM case 3 and 5]

In this case, the TPM v3 waits for the start of a new PWM period to begin using the new duty cycle setting. Instead, the TPM v2 changes the channel output at the middle of the current PWM period (when the count reaches 0x0000).

— TPMxCnVH:L is changed from a non-zero value to 0x0000 [SE110-TPM case 4]

In this case, the TPM v3 finishes the current PWM period using the old duty cycle setting. Instead, the TPM v2 finishes the current PWM period using the new duty cycle setting.

6. Write to TPMxMODH:L registers in BDM mode (Section 16.3.3, "TPM Counter Modulo Registers (TPMxMODH:TPMxMODL))

In the TPM v3 a write to TPMxSC register in BDM mode clears the write coherency mechanism of TPMxMODH:L registers. Instead, in the TPM v2 this coherency mechanism is not cleared when there is a write to TPMxSC register.

7. Update of EPWM signal when CLKSB:CLKSA = 00

In the TPM v3 if CLKSB:CLKSA = 00, then the EPWM signal in the channel output is not update (it is frozen while CLKSB:CLKSA = 00). Instead, in the TPM v2 the EPWM signal is updated at the next rising edge of bus clock after a write to TPMxCnSC register.

The Figure 0-1 and Figure 0-2 show when the EPWM signals generated by TPM v2 and TPM v3 after the reset (CLKSB:CLKSA = 00) and if there is a write to TPMxCnSC register.

17.2.3 BDC Commands

BDC commands are sent serially from a host computer to the BKGD pin of the target HCS08 MCU. All commands and data are sent MSB-first using a custom BDC communications protocol. Active background mode commands require that the target MCU is currently in the active background mode while non-intrusive commands may be issued at any time whether the target MCU is in active background mode or running a user application program.

Table 17-1 shows all HCS08 BDC commands, a shorthand description of their coding structure, and the meaning of each command.

Coding Structure Nomenclature

This nomenclature is used in Table 17-1 to describe the coding structure of the BDC commands.

		Commands begin with an 8-bit hexadecimal command code in the host-to-target direction (most significant bit first)
/	=	separates parts of the command
d	=	delay 16 target BDC clock cycles
AAAA	=	a 16-bit address in the host-to-target direction
RD	=	8 bits of read data in the target-to-host direction
WD	=	8 bits of write data in the host-to-target direction
RD16	=	16 bits of read data in the target-to-host direction
WD16	=	16 bits of write data in the host-to-target direction
SS	=	the contents of BDCSCR in the target-to-host direction (STATUS)
CC	=	8 bits of write data for BDCSCR in the host-to-target direction (CONTROL)
RBKP	=	16 bits of read data in the target-to-host direction (from BDCBKPT breakpoint register)
WBKP	=	16 bits of write data in the host-to-target direction (for BDCBKPT breakpoint register)

The SYNC command is unlike other BDC commands because the host does not necessarily know the correct communications speed to use for BDC communications until after it has analyzed the response to the SYNC command.

To issue a SYNC command, the host:

- Drives the BKGD pin low for at least 128 cycles of the slowest possible BDC clock (The slowest clock is normally the reference oscillator/64 or the self-clocked rate/64.)
- Drives BKGD high for a brief speedup pulse to get a fast rise time (This speedup pulse is typically one cycle of the fastest clock in the system.)
- Removes all drive to the BKGD pin so it reverts to high impedance
- Monitors the BKGD pin for the sync response pulse

The target, upon detecting the SYNC request from the host (which is a much longer low time than would ever occur during normal BDC communications):

- Waits for BKGD to return to a logic high
- Delays 16 cycles to allow the host to stop driving the high speedup pulse
- Drives BKGD low for 128 BDC clock cycles
- Drives a 1-cycle high speedup pulse to force a fast rise time on BKGD
- Removes all drive to the BKGD pin so it reverts to high impedance

The host measures the low time of this 128-cycle sync response pulse and determines the correct speed for subsequent BDC communications. Typically, the host can determine the correct communication speed within a few percent of the actual target speed and the communication protocol can easily tolerate speed errors of several percent.

17.2.4 BDC Hardware Breakpoint

The BDC includes one relatively simple hardware breakpoint that compares the CPU address bus to a 16-bit match value in the BDCBKPT register. This breakpoint can generate a forced breakpoint or a tagged breakpoint. A forced breakpoint causes the CPU to enter active background mode at the first instruction boundary following any access to the breakpoint address. The tagged breakpoint causes the instruction opcode at the breakpoint address to be tagged so that the CPU will enter active background mode rather than executing that instruction if and when it reaches the end of the instruction queue. This implies that tagged breakpoints can only be placed at the address of an instruction opcode while forced breakpoints can be set at any address.

The breakpoint enable (BKPTEN) control bit in the BDC status and control register (BDCSCR) is used to enable the breakpoint logic (BKPTEN = 1). When BKPTEN = 0, its default value after reset, the breakpoint logic is disabled and no BDC breakpoints are requested regardless of the values in other BDC breakpoint registers and control bits. The force/tag select (FTS) control bit in BDCSCR is used to select forced (FTS = 1) or tagged (FTS = 0) type breakpoints.

The on-chip debug module (DBG) includes circuitry for two additional hardware breakpoints that are more flexible than the simple breakpoint in the BDC module.

17.3 On-Chip Debug System (DBG)

Because HCS08 devices do not have external address and data buses, the most important functions of an in-circuit emulator have been built onto the chip with the MCU. The debug system consists of an 8-stage FIFO that can store address or data bus information, and a flexible trigger system to decide when to capture bus information and what information to capture. The system relies on the single-wire background debug system to access debug control registers and to read results out of the eight stage FIFO.

The debug module includes control and status registers that are accessible in the user's memory map. These registers are located in the high register space to avoid using valuable direct page memory space.

Most of the debug module's functions are used during development, and user programs rarely access any of the control and status registers for the debug module. The one exception is that the debug system can provide the means to implement a form of ROM patching. This topic is discussed in greater detail in Section 17.3.6, "Hardware Breakpoints."

17.3.1 Comparators A and B

Two 16-bit comparators (A and B) can optionally be qualified with the R/W signal and an opcode tracking circuit. Separate control bits allow you to ignore R/W for each comparator. The opcode tracking circuitry optionally allows you to specify that a trigger will occur only if the opcode at the specified address is actually executed as opposed to only being read from memory into the instruction queue. The comparators are also capable of magnitude comparisons to support the inside range and outside range trigger modes. Comparators are disabled temporarily during all BDC accesses.

The A comparator is always associated with the 16-bit CPU address. The B comparator compares to the CPU address or the 8-bit CPU data bus, depending on the trigger mode selected. Because the CPU data bus is separated into a read data bus and a write data bus, the RWAEN and RWA control bits have an additional purpose, in full address plus data comparisons they are used to decide which of these buses to use in the comparator B data bus comparisons. If RWAEN = 1 (enabled) and RWA = 0 (write), the CPU's write data bus is used. Otherwise, the CPU's read data bus is used.

The currently selected trigger mode determines what the debugger logic does when a comparator detects a qualified match condition. A match can cause:

- Generation of a breakpoint to the CPU
- Storage of data bus values into the FIFO
- Starting to store change-of-flow addresses into the FIFO (begin type trace)
- Stopping the storage of change-of-flow addresses into the FIFO (end type trace)

17.3.2 Bus Capture Information and FIFO Operation

The usual way to use the FIFO is to setup the trigger mode and other control options, then arm the debugger. When the FIFO has filled or the debugger has stopped storing data into the FIFO, you would read the information out of it in the order it was stored into the FIFO. Status bits indicate the number of words of valid information that are in the FIFO as data is stored into it. If a trace run is manually halted by writing 0 to ARM before the FIFO is full (CNT = 1:0:0:0), the information is shifted by one position and

Table 17-2. BDCSCR Register Field Descriptions (continued)

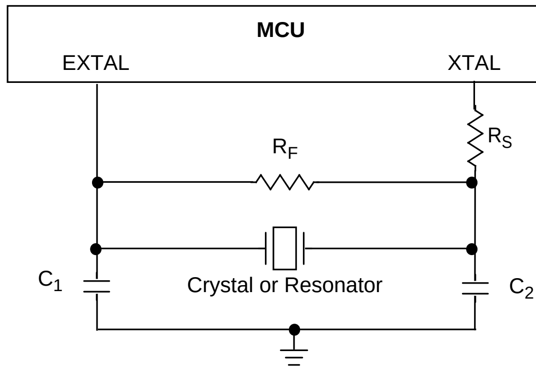
Field	Description
2 WS	**Wait or Stop Status** — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands. 0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active) 1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode
1 WSF	**Wait or Stop Failure Status** — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.) 0 Memory access did not conflict with a wait or stop instruction 1 Memory access command failed because the CPU entered wait or stop mode
0 DVF	**Data Valid Failure Status** — This status bit is not used in the MC9S08DZ60 Series because it does not have any slow access memory. 0 Memory access did not conflict with a slow memory access 1 Memory access command failed because CPU was not finished with a slow memory access

17.4.1.2 BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ_BKPT and WRITE_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to Section 17.2.4, “BDC Hardware Breakpoint.”

17.4.2 System Background Debug Force Reset Register (SBDFR)

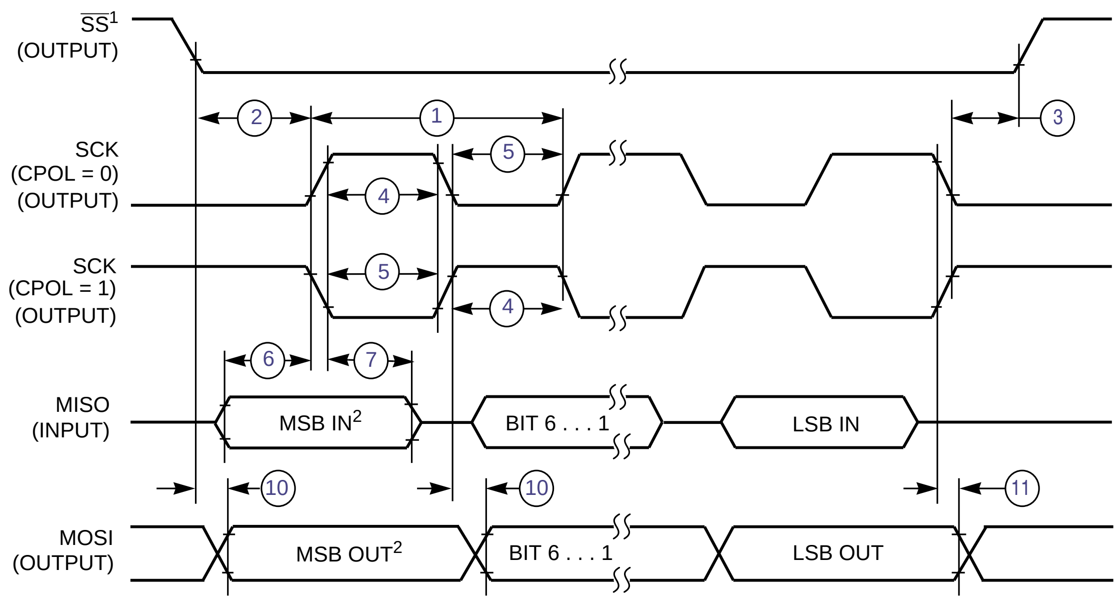
This register contains a single write-only control bit. A serial background mode command such as WRITE_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.



A.11 MCG Specifications

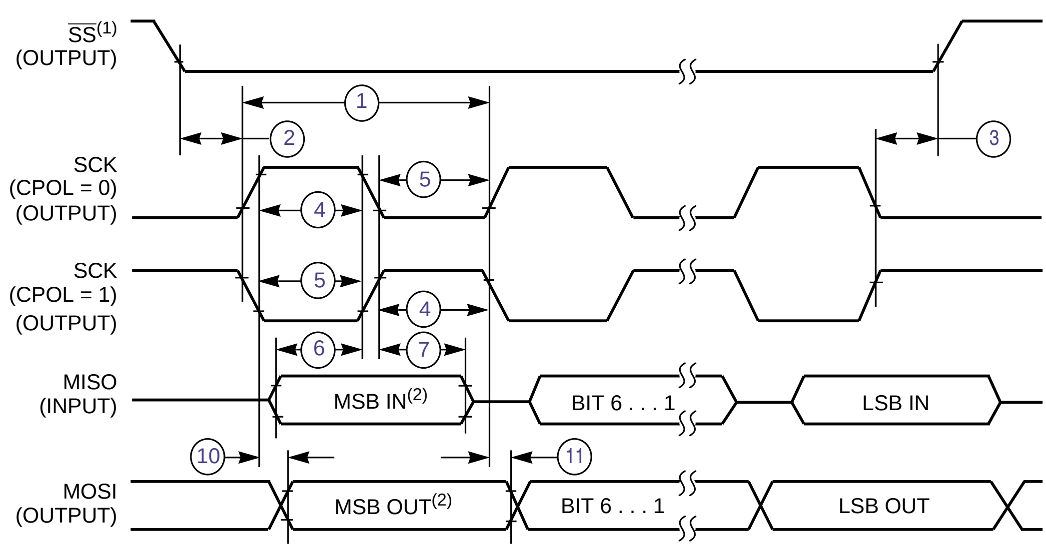
Table A-12. MCG Frequency Specifications (Temperature Range = –40 to 125°C Ambient)

Num	C	Rating	Symbol	Min	Typical	Max	Unit
1	P	Internal reference frequency - factory trimmed at V_{DD} = 5 V and temperature = 25 °C	f_{int_ft}	—	31.25	—	kHz
2	P	Average internal reference frequency - untrimmed [1]	f_{int_ut}	25	32.7	41.66	kHz
3	P	Average internal reference frequency - user trimmed	f_{int_t}	31.25	—	39.0625	kHz
4	D	Internal reference startup time	t_{irefst}	—	60	100	us
5	—	DCO output frequency range - untrimmed [1] value provided for reference: f_{dco_ut} = 1024 X f_{int_ut}	f_{dco_ut}	25.6	33.48	42.66	MHz
6	P	DCO output frequency range - trimmed	f_{dco_t}	32	—	40	MHz
7	C	Resolution of trimmed DCO output frequency at fixed voltage and temperature (using FTRIM)	$\Delta f_{dco\_res\_t}$	—	$\pm$ 0.1	$\pm$ 0.2	$\%f_{dco}$
8	C	Resolution of trimmed DCO output frequency at fixed voltage and temperature (not using FTRIM)	$\Delta f_{dco\_res\_t}$	—	$\pm$ 0.2	$\pm$ 0.4	$\%f_{dco}$
9	P	Total deviation of trimmed DCO output frequency over voltage and temperature	Δf_{dco_t}	—	+ 0.5 -1.0	$\pm$ 2	$\%f_{dco}$
10	C	Total deviation of trimmed DCO output frequency over fixed voltage and temperature range of 0 - 70 °C	Δf_{dco_t}	—	$\pm$ 0.5	$\pm$ 1	$\%f_{dco}$
11	C	FLL acquisition time [2]	$t_{fll\_acquire}$	—	—	1	ms
12	D	PLL acquisition time [3]	$t_{pll\_acquire}$	—	—	1	ms
13	C	Long term Jitter of DCO output clock (averaged over 2ms interval) [4]	C_{Jitter}	—	0.02	0.2	$\%f_{dco}$
14	D	VCO operating frequency	f_{vco}	7.0	—	55.0	MHz
15	D	PLL reference frequency range	f_{pll_ref}	1.0	—	2.0	MHz
16	T	RMS frequency variation of a single clock cycle measured 2 ms after reference edge.[5]	$f_{pll\_cycjit\_2ms}$	—	0.590[4]	—	$\%f_{pll}$
17	T	Maximum frequency variation averaged over 2 ms window.	$f_{pll\_maxjit\_2ms}$	—	0.001	—	$\%f_{pll}$



NOTES:
1. $\overline{SS}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-7. SPI Master Timing (CPHA = 0)



NOTES:
1. $\overline{SS}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-8. SPI Master Timing (CPHA = 1)

Table B-5. Mode, Edge, and Level Selection

CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
X	XX	00	Pin not used for TPM channel; use as an external clock for the TPM or revert to general-purpose I/O	
0	00	01	Input capture	Capture on rising edge only
		10		Capture on falling edge only
		11		Capture on rising or falling edge
	01	00	Output compare	Software compare only
		01		Toggle output on compare
		10		Clear output on compare
		11		Set output on compare
	1X	10	Edge-aligned PWM	High-true pulses (clear output on compare)
		X1		Low-true pulses (set output on compare)
1	XX	10	Center-aligned PWM	High-true pulses (clear output on compare-up)
		X1		Low-true pulses (set output on compare-up)

If the associated port pin is not stable for at least two bus clock cycles before changing to input capture mode, it is possible to get an unexpected indication of an edge trigger. Typically, a program would clear status flags after changing channel configuration bits and before enabling channel interrupts or using the status flags to avoid any unexpected behavior.

B.2.5 Timer Channel Value Registers (TPMxCnVH:TPMxCnVL)

These read/write registers contain the captured TPM counter value of the input capture function or the output compare value for the output compare or PWM functions. The channel value registers are cleared by reset.

	7	6	5	4	3	2	1	0
R W	Bit 15	14	13	12	11	10	9	Bit 8
Reset	0	0	0	0	0	0	0	0

Figure B-8. Timer Channel Value Register High (TPMxCnVH)

	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	0	0	0	0	0	0	0	0

Figure B-9. Timer Channel Value Register Low (TPMxCnVL)